

ABSTRACT OF THE DISCLOSURE

The present invention provides a resin composition for semiconductor encapsulation excellent in reliability in humidity resistance and storage stability as well as in dischargeability and coatability, a semiconductor device encapsulated with the resin composition for semiconductor encapsulation and a process for the production of the semiconductor device. The resin composition for semiconductor encapsulation comprises the following components (A) to (D) and has a viscosity of 700 Pa·s or higher at 25°C and 500 Pa·s or lower at 80°C:

- (A) an epoxy resin;
- (B) an acid anhydride-based curing agent;
- (C) a latent curing accelerator; and
- (D) an inorganic filler.

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